

LINEAR TECHNOLOGY MATERIALS DECLARATION

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(Engineering Calculation)

PDIP

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TOTAL MASS (g) : 0.502036

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004583 | 1000000 | 9128.8226562 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000256 | 1000000 | 509.923278809 | | |
| Lead Frame | A42 | Copper (Cu) | 7440-50-8 | 0.000000 | 0 | 0 | | |
| | | Iron (Fe) | 7439-89-6 | 0.089088 | 580000 | 177453.296875 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.064512 | 420000 | 128500.65625 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.153600 | 1000000 | 305953.96875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.012410 | 1000000 | 24719.9042969 | | |
| | | External Plating Total: | | | | 0.012410 | 1000000 | 24719.9042969 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001228 | 1000000 | 2446.03808594 | | |
| Internal Plating Total: | | | | 0.001228 | 1000000 | 2446.03808594 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001231 | 750000 | 2452.01342773 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000410 | 250000 | 816.673950195 | | |
| Die Attach Total: | | | | 0.001641 | 1000000 | 3268.68774414 | | |
| Encapsulation | FILLED EPOXY RESIN | Resin (EP) | | 0.078728 | 240000 | 156817.328125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.003280 | 10000 | 6533.39160156 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.236183 | 720000 | 470450 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.009841 | 30000 | 19602.1660156 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000000 | 0 | 0 | | |
| | | Encapsulation Total: | | | | 0.328032 | 1000000 | 653402.875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000286 | 1000000 | 569.679870605 | | |
| | | | | | TOTAL MASS (g) : | 0.502036 | | |